Uyemura to Exhibit and Speak
at IPC APEX EXPO 2019

Southington, CT. December 3, 2018. Uyemura, the global leader in PCB final finishes, will exhibit several unique technologies – each designed to meet a specific need - as board shops face unprecedented demands for thicker gold, void-free via fill and low corrosion.

Rich DePoto

Jon Bengston

Industry experts who have been intimately involved with process development – and field engineers with extensive production experience - will be in Booth 533 for consultations and technical discussions during the 3-day conference.

Highlights of Uyemura's exhibit include TWX-40 a reduction-assisted immersion bath that meets the demand for gold deposits (up to 8 µin) in ENIG and ENEPIG systems while preserving electroless nickel integrity; Talon electroless/alloyed palladium phos for ENEPIG; and EVF-YF-4 via fill copper, which pattern plates uniformly, and plates through-holes and blind vias simultaneously.

Rich DePoto, Uyemura Manager of Business Development will present *"Contrasting Soldering Results of ENIG and EPIG, Post Steam Aging"* as part of the technical program. Jon Bengston, Manager of Research & Development, is the paper's author. ENIG, (electroless nickel immersion gold) is well-established for enhancing and preserving the

solderability of copper circuits. EPIG (electroless palladium immersion gold) is a newer surface finish, also for enhancing solderability but with the advantage of a deposit layer that's free of electroless nickel. This feature has become increasingly important with the increasing use of High Frequency PWB designs. DePoto will examine these finishes and their soldering characteristics as-plated and after steam aging, and explain the performance deviation.

To schedule a meeting during APEX, contact Uyemura at (860) 793-4011, email to rdepoto@uyemura.com, or visit Booth 533 at APEX, January 29-31.

For more information, contact Uyemura, 240 Town Line Road • Southington, CT 06489. (860) 793-4011 www.uyemura.com